



#12/B
10/29/01
Hayes

Attorney Docket No.: SEL-173

In re Application of:)
Ohtani et al.)
Serial No.: 09/535,836)
Filed: March 28, 2000)
For: Semiconductor Device)
and the Fabricating)
Method Thereof)
Art Group: 2811)
Examiner: H. Vu)

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to: Commissioner for Patents, Washington, D.C. 20231 on October 12, 2001

Signature

Name Bobbi Wilson

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AMENDMENT

Commissioner for Patents
Washington, D.C. 20231

Sir:

Please amend the above-identified application as follows:

IN THE SPECIFICATION:

Please amend the title to read as follows:

Semiconductor Device Having Multi-layer Wiring

IN THE CLAIMS:

Please amend claims 1, 7, 19, 28 and 34 as follows:

1. (Amended) A semiconductor device comprising:

a first insulating film comprising an organic material formed over a conductive layer;

10/16/2001 NM0HMM1 00000093 09535836 a first metallic layer formed on said first insulating film;

01 FC:103 108.00 DP
02 FC:102 84.00 DP